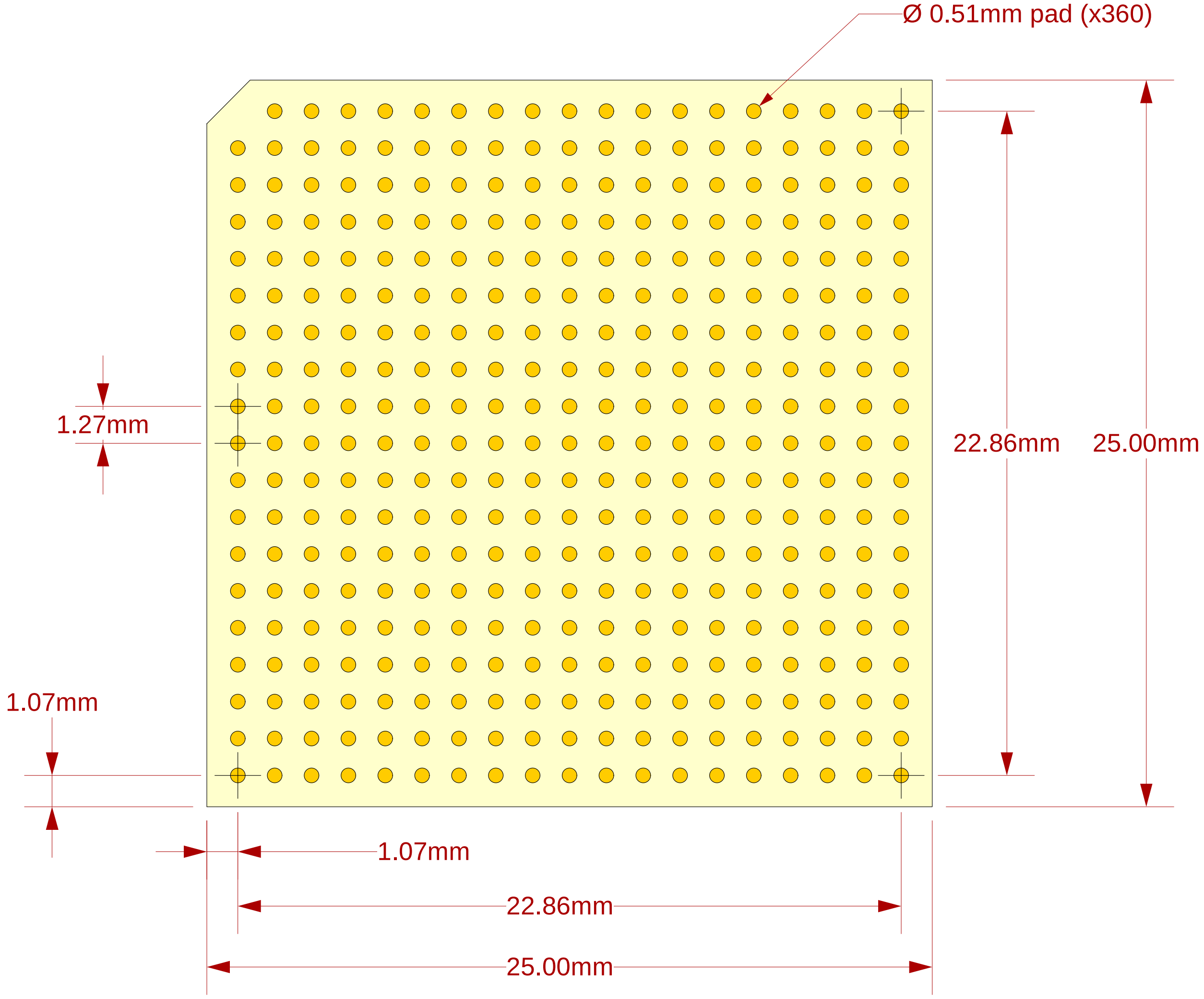
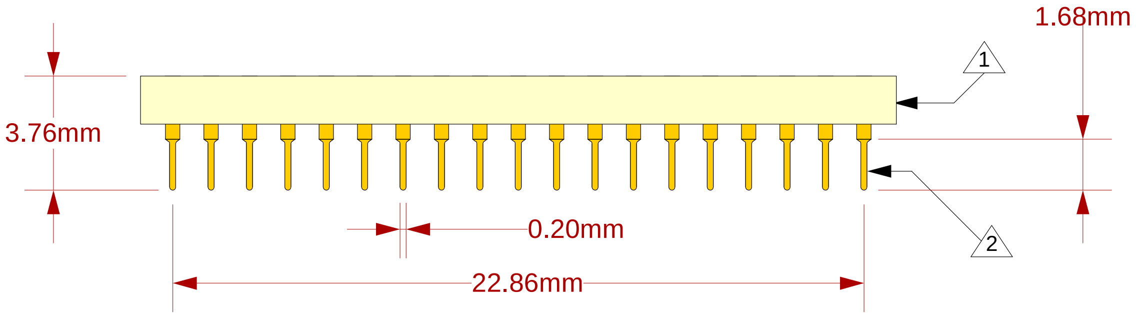
TOP VIEW



SIDE VIEW



1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"]
FR4/G10 or equivalent high temp material.

2 Pins: material- Brass Alloy 360 1/2 hard; finish-
0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).

<u>Description:</u> Giga-snaP BGA SMT Land Socket
360 position BGA surface mount land pattern to terminal pins (1.27mm [0.050"] centers, 19x19 array).

<u>Tolerances:</u> diameters ±0.03mm [±0.001”], PCB perimeters ±0.13mm [±0.005”], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005”] unless stated otherwise. Materials and specifications are subject to change without notice.

LS-BGA360A-31 Drawing	Status: Released	Scale: 4:1	Rev: A
© 2013 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com	Drawing: S. Faiz	Date: 11/13/13	
	File: LS-BGA360A-31 Dwg	Modified:	